

ABSTRACT

SEMICONDUCTOR DEVICE MANUFACTURING DEVICE AND MANUFACTURING METHOD

5 A semiconductor device manufacturing device (10) is provided with a stage (12), a
mounting tool (20), a pressurizing mechanism (22) for causing the mounting tool (20) to be moved
vertically to apply a load to a chip (100), and a controller (16). The controller (16) is configured
to perform, after the chip (100) has landed and until a bump (104) melts: a first process in which
the chip (100) is heated by the mounting tool (20) and a command position P^* for the pressurizing
10 mechanism (22) is updated, as required, so as to make a position deviation ΔP^* constant; and a
detection process for detecting melting of the bump on the basis of a decrease in a pressing load.

Figure 1